

CMOS Digital Integrated Circuits Silicon Monolithic

# TC4S66F,TC4S66FU

#### 1. Functional Description

Bilateral Switch

#### 2. General

TC4S66F, TC4S66FU contains one circuit of bidirectional switches.

When control input, CONT is set to "H" level, the impedance between input and output of the switch becomes low and when it is set to "L" level, the switch becomes high.

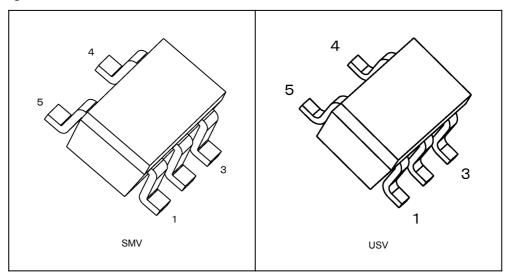
This can be applied for switching of analog signals and digital signals.

#### 3. Features

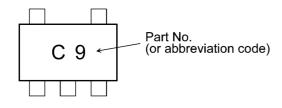
(1) ON resistance:  $R_{ON} = 250 \Omega$  (Typ.) at  $V_{DD} - V_{SS} = 5 V$  $R_{ON} = 110 \Omega$  (Typ.) at  $V_{DD} - V_{SS} = 10 \text{ V}$  $R_{\rm ON}$  = 70  $\Omega$  (Typ.) at  $V_{\rm DD}$  -  $V_{\rm SS}$  = 15 V

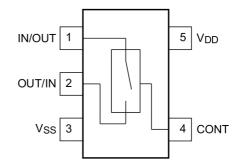
(2)OFF resistance:  $R_{OFF}$  (Typ.) >  $10^9 \Omega$ 

#### 4. Packaging



#### 5. Marking and Pin Assignment





Marking

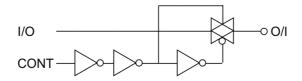
Pin Assignment (Top view)

Start of commercial production

1988-01



#### 6. Logic Diagram



#### 7. Truth Table

Control	Impedance between IN/OUT-OUT/IN (Note 1)
Н	0.5 to 5.0 $\times$ 10² $\Omega$
L	> 10 <sup>9</sup> Ω

Note 1: See electrical characteristics

### 8. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Rating	Unit
DC Supply voltage	$V_{DD}$	V <sub>SS</sub> - 0.5 to V <sub>SS</sub> + 20	V
Input voltage	V <sub>IN</sub>	V <sub>SS</sub> - 0.5 to V <sub>DD</sub> + 0.5	
Switch I/O voltage.	V <sub>I/O</sub>	V <sub>SS</sub> - 0.5 to V <sub>DD</sub> + 0.5	
Power dissipation	P <sub>D</sub>	200	mW
Potential difference across I/O during ON	V <sub>I</sub> -V <sub>O</sub>	±0.5	٧
Input current	I <sub>IN</sub>	±10	mA
Operation temperature range	T <sub>opr</sub>	-40 to 85	°C
Storage temperature	T <sub>stg</sub>	-65 to 150	°C
Lead temperature (10 s)	TL	260	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 9. Operating Ranges (V<sub>SS</sub> = 0 V)

Characteristics	Symbol	Min	Тур.	Max	Unit
DC Supply voltage	$V_{DD}$	3	_	18	V
Switch I/O voltage.	V <sub>I/O</sub>	0		$V_{DD}$	V



#### 10. Electrical Characteristics

## 10.1. Electrical Characteristics (Unless otherwise specified, $T_a$ = 25 °C)

Characteristics	Symbol	Test Condition	V <sub>DD</sub> (V)	Min	Тур.	Max	Unit
High-level input voltage	V <sub>IH</sub>	I <sub>IS</sub>   = 10 μA	5	3.5	2.75	_	V
			10	7.0	5.50	_	
			15	11.0	8.25	_	
Low-level input voltage	V <sub>IL</sub>	I <sub>IS</sub>   = 10 μA	5	_	2.25	1.5	
			10	_	4.5	3.0	
			15	_	6.75	4.0	
ON-resistance	R <sub>ON</sub>	$0 \le V_{IS} \le V_{DD}$	5	_	290	950	Ω
		$R_L = 10 \text{ k}\Omega$	10	_	120	250	
			15	_	85	160	
Power-OFF leakage current	I <sub>OFF</sub>	V <sub>IN</sub> = 18 V, V <sub>OUT</sub> = 0 V	18	_	±0.1	±100	nA
		$V_{IN} = 0 \text{ V}, V_{OUT} = 18 \text{ V}$	18	_	±0.1	±100	
Quiescent device current	I <sub>DD</sub>	$V_{IN} = V_{DD}, V_{SS}$	5	_	0.001	0.25	μА
			10	_	0.001	0.5	
			15	_	0.002	1.0	
High level input current	I <sub>IH</sub>	V <sub>IH</sub> = 18 V	18		10-5	0.1	μА
Low level input current	I <sub>IL</sub>	V <sub>IL</sub> = 0 V	18	_	-10-5	-0.1	

## 10.2. Electrical Characteristics (Unless otherwise specified, T<sub>a</sub> = -40 °C)

Characteristics	Symbol	Test Condition	V <sub>DD</sub> (V)	Min	Max	Unit
High-level input voltage	V <sub>IH</sub>	I <sub>IS</sub>   = 10 μA	5	3.5	_	V
			10	7.0	_	
			15	11.0	_	
Low-level input voltage	V <sub>IL</sub>	I <sub>IS</sub>   = 10 μA	5	_	1.5	
			10	_	3.0	
			15	_	4.0	
ON-resistance	R <sub>ON</sub>	$0 \le V_{IS} \le V_{DD}$	5	_	800	Ω
		$R_L = 10 \text{ k}\Omega$	10	_	210	
			15	_	140	
Power-OFF leakage current	I <sub>OFF</sub>	V <sub>IN</sub> = 18 V, V <sub>OUT</sub> = 0 V	18	_	±100	nA
		$V_{IN} = 0 \text{ V}, V_{OUT} = 18 \text{ V}$	18	_	±100	
Quiescent device current	I <sub>DD</sub>	$V_{IN} = V_{DD}, V_{SS}$	5	_	0.25	μА
			10	_	0.5	
			15	_	1.0	
High level input current	I <sub>IH</sub>	V <sub>IH</sub> = 18 V	18	_	0.1	μА
Low level input current	I <sub>IL</sub>	V <sub>IL</sub> = 0 V	18		-0.1	



## 10.3. Electrical Characteristics (Unless otherwise specified, T<sub>a</sub> = 85 °C)

Characteristics	Symbol	Test Condition	V <sub>DD</sub> (V)	Min	Max	Unit
High-level input voltage	V <sub>IH</sub>	I <sub>IS</sub>   = 10 μA	5	3.5	_	V
			10	7.0	_	
			15	11.0	_	
Low-level input voltage	V <sub>IL</sub>	I <sub>IS</sub>   = 10 μA	5	_	1.5	
			10	_	3.0	
			15	_	4.0	
ON-resistance	R <sub>ON</sub>	$0 \le V_{IS} \le V_{DD}$	5	_	1200	Ω
		$R_L = 10 \text{ k}\Omega$	10	_	300	
			15	_	200	
Power-OFF leakage current	I <sub>OFF</sub>	V <sub>IN</sub> = 18 V, V <sub>OUT</sub> = 0 V	18	_	±1000	nA
		$V_{IN} = 0 \text{ V}, V_{OUT} = 18 \text{ V}$	18	_	±1000	
Quiescent device current	I <sub>DD</sub>	$V_{IN} = V_{DD}, V_{SS}$	5	_	7.5	μА
			10	_	15	
			15	_	30	
High level input current	I <sub>IH</sub>	V <sub>IH</sub> = 18 V	18	_	1.0	μА
Low level input current	I <sub>IL</sub>	V <sub>IL</sub> = 0 V	18	_	-1.0	

## 11. Switching Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Test Condition	V <sub>SS</sub> (V)	V <sub>DD</sub> (V)	Min	Тур.	Max	Unit			
Propagation delay time(IN-	t <sub>PLH</sub> ,t <sub>PHL</sub>		C <sub>L</sub> = 50 pF	0	5		15	40	ns			
OUT)				0	10	-	8	20				
				0	15	1	5	15				
Propagation delay time	t <sub>PZL</sub> t <sub>PZH</sub>		$R_L = 1 k\Omega$	0	5	ı	55	120	ns			
(CONTROL-OUT)			C <sub>L</sub> = 50 pF	0	10		25	40				
				0	15	-	20	30				
Propagation delay time	t <sub>PLZ</sub> t <sub>PHZ</sub>		$R_L = 1 k\Omega$	0	5	_	45	80	ns			
(CONTROL-OUT)			C <sub>L</sub> = 50 pF	0	10		30	70				
				0	15		25	60				
Max.Control input repetition	f <sub>MAX(C)</sub>		R <sub>L</sub> = 1 kΩ	0	5		10	_	MHz			
rate		CL				C <sub>L</sub> = 50 pF	0	10		12	_	
				0	15	_	12	_				
Maximum frequency response	f <sub>MAX(I-O)</sub>	(Note 1)	$R_L = 1 \text{ k}\Omega$ $C_L = 50 \text{ pF}$	-5	5	_	30	_				
Total Harmonic Distortion	THD		$R_L$ = 10 kΩ f = 1 kHz	-5	5	_	0.03	_	%			
Feed through attenuation (SWITCH OFF)	FTH	(Note 3)	$R_L = 1 k\Omega$	-5	5	_	600	_	kHz			
Crosstalk(CONTROL-OUT)	Xtalk		$R_{IN} = 1 k\Omega$	0	5	_	200	_	mV			
			$R_{OUT} = 10 \text{ k}\Omega$ $C_L = 15 \text{ pF}$	0	10	_	400	_				
			OL - 13 pi	0	15	_	600	_				
Input capacitance	C <sub>IN</sub>		Control input				5	7.5	pF			
			Switch I/O				10	_				
Feedthrough capacitance	C <sub>IOS</sub>		_			_	0.5	_	pF			

Note 1: The frequency at 20 log10  $V_{OS}/V_{IS}$  = -3 dB shall be  $f_{MAX(I-O)}$  using sine wave of  $\pm 2.5$  Vp-p for  $V_{IS}$ .

Note 2:  $V_{IS}$  shall be sine wave of  $\pm 2.5$  V.

Note 3: The frequency at 20 log10  $V_{OS}/V_{IS}$  = -50 dB shall be the feed through using of  $\pm 2.5$  Vp-p.



#### 11.1. Switching Test Circuit

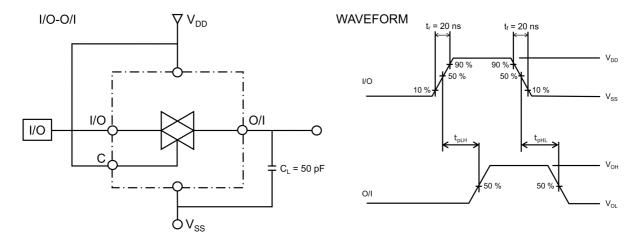


Fig. 11.1.1 t<sub>pLH</sub>, t<sub>pHL</sub>

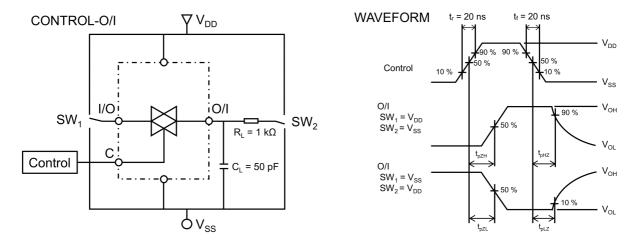


Fig. 11.1.2  $t_{pZL}.t_{pZH}$ ,  $t_{pLZ}$ ,  $t_{pHZ}$ 

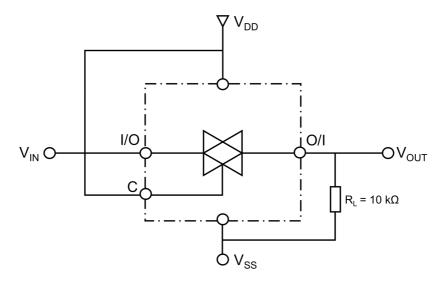


Fig. 11.1.3 R<sub>ON</sub>



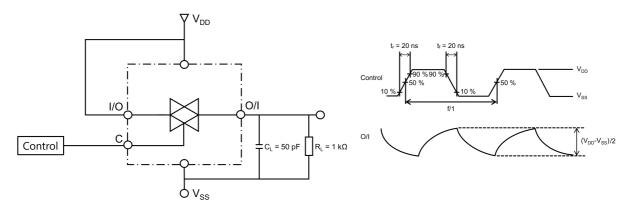


Fig. 11.1.4 f<sub>MAX</sub> (C)

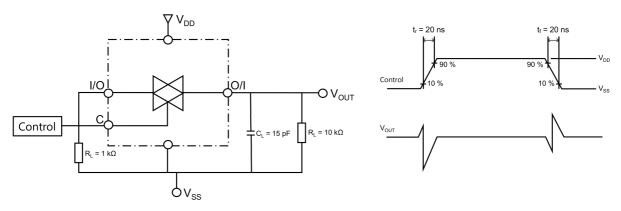
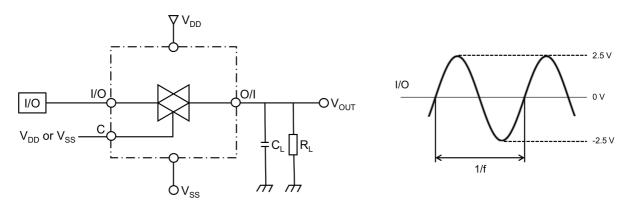


Fig. 11.1.5 CROSSTALK(CONTROL INPUT)



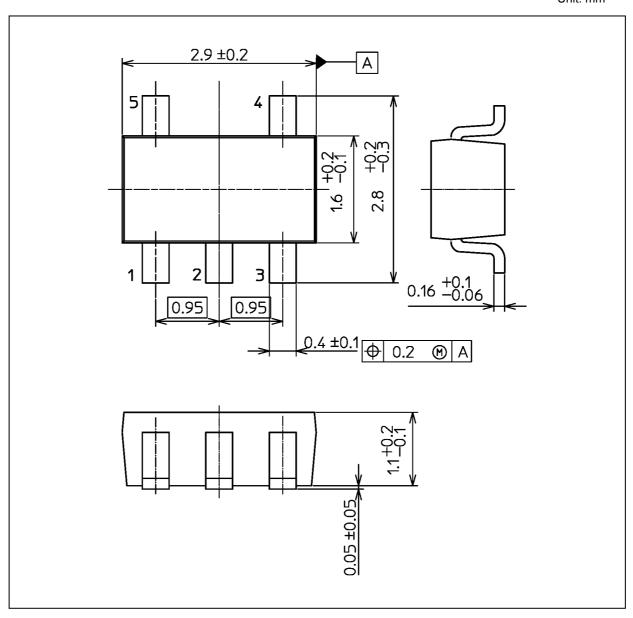
C<sub>L</sub>, R<sub>L</sub>: Reference to Test Condition

Fig. 11.1.6 TOTAL HARMONIC DISTORTION, f<sub>MAX</sub>(I/O-O/I), FEEDTHRU(SWITCH OFF)



## **Package Dimensions**

Unit: mm



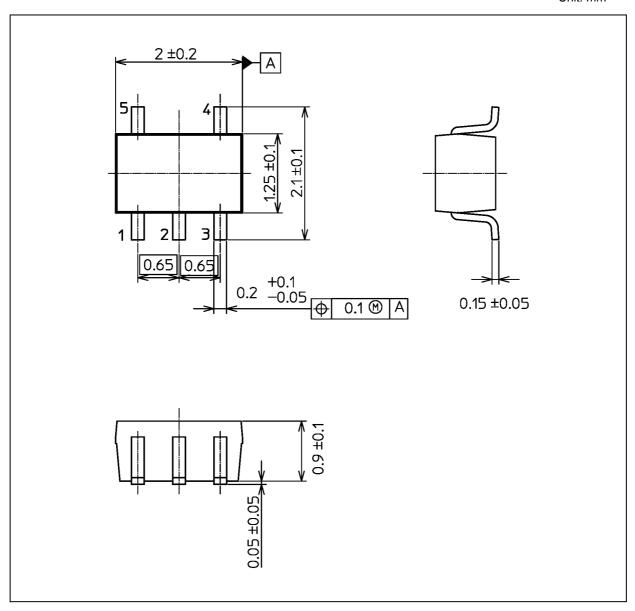
Weight: 14 mg (typ.)

	Package Name(s)
JEDEC: SOT-25	
Nickname: SMV	



## **Package Dimensions**

Unit: mm



Weight: 0.006 g (typ.)

	Package Name(s)
JEDEC: SOT-353	
Nickname: USV	



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